

UDFN4 1.2x1.6, 0.5P CASE 517CE **ISSUE B**

DATE 03 APR 2012

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM THE TERMINAL TIPS.
 4. PACKAGE DIMENSIONS EXCLUSIVE OF
- BURRS AND MOLD FLASH.

| | MILLIMETERS | | |
|-----|-------------|------|------|
| DIM | MIN | NOM | MAX |
| Α | 0.45 | 0.50 | 0.55 |
| A1 | 0.00 | | 0.05 |
| А3 | 0.13 REF | | |
| b | 0.25 | 0.30 | 0.35 |
| D | 1.20 BSC | | |
| D2 | 0.76 | 0.86 | 0.96 |
| Е | 1.60 BSC | | |
| E2 | 0.40 | 0.50 | 0.60 |
| е | 0.50 BSC | | |
| L | 0.20 | 0.30 | 0.40 |
| L1 | | | 0.15 |

GENERIC MARKING DIAGRAM*



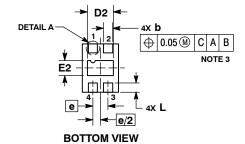
XX = Specific Device Code

= Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

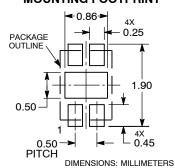
Α ∢DI→ В **DETAIL A** PIN ONE REFERENCE ALTERNATE TERMINAL CONSTRUCTIONS 2X | 0.05 С 0.05 C **EXPOSED** Cu MOLD CMPD **TOP VIEW DETAIL B** 0.05 C **DETAIL B** ALTERNATE CONSTRUCTION 0.05 C

A1 C SEATING



SIDE VIEW

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| DOCUMENT NUMBER: | 98AON66552E | Electronic versions are uncontrolled | |
|------------------|---------------------------|---|-------------|
| STATUS: | ON SEMICONDUCTOR STANDARD | accessed directly from the Document F versions are uncontrolled except w | , , |
| NEW STANDARD: | | "CONTROLLED COPY" in red. | |
| DESCRIPTION: | UDFN4, 1.2X1.6, 0.5P | | PAGE 1 OF 2 |



| DOCUMENT | NUMBER: |
|------------|---------|
| 98AON66552 | E |

PAGE 2 OF 2

| ISSUE | REVISION | DATE |
|-------|--|-------------|
| 0 | RELEASED FOR PRODUCTION. REQ. BY B. MARQUIS. | 31 JAN 2012 |
| Α | ADDED GENERIC MARKING DIAGRAM. REQ. BY B. MARQUIS. | 09 FEB 2012 |
| В | CORRECTED SOLDERING FOOTPRINT AND MARKING DIAGRAM. REQ. BY B. MARQUIS. | 03 APR 2012 |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, ne patern rights for the rights of others. Scilled products are not designed, interfleed, or adultorized for use as components in systems interfleed for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

© Semiconductor Components Industries, LLC, 2012 Case Outline Number: April, 2012 - Rev. B 517CF